

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

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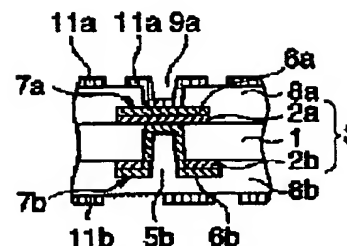
APPLICATION DATE : 09-03-98  
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APPLICANT : ELNA CO LTD;

INVENTOR : FUKUDA NAOTO;

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TITLE : MULTI-LAYER PRINTED WIRING  
BOARD AND MANUFACTURE  
THEREOF



**ABSTRACT :** PROBLEM TO BE SOLVED: To provide a printed wiring board, together with its manufacturing method wherein a hole of an inner-layer material and that of a built-up layer are provided at the same position, for higher density and smaller size.

**SOLUTION:** On a core material 3, a metal-plated non-through hole 5b which is not penetrating but reaching a circuit pattern 7a of the other surface from a circuit pattern 7b of one surface is provided, and at the same position as the non-through hole 5b of the inner-layer material of a built-up layer 8a on the other side of the core material 3, a metal-plated non-through hole 9b to the circuit pattern 7a on the other surface of the inner-layer material from the surface of the built-up layer 8a is provided.

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